

REMARKS

Original claims 1-58 have been canceled. New claims 59-80 have been added.

Claims 59-76 are directed to an electronic assembly. As shown in Figure 4, the electronic assembly 22 includes a substrate 24 having a plurality of contact pads 28. The electronic assembly 22 also includes a component 50 on the substrate 24 having a plurality of external contacts 10 in electrical communication with the contact pads 28. The component 50 includes a polymer layer 48, or polymer rings 54 (Figure 5A), substantially surrounding and adhering to the external contacts 10. The electronic assembly 22 also includes an underfill layer 56 formed in a gap between the component 50 and the substrate 24.

Claims 77-80 are directed to a method for fabricating a semiconductor component 50, which uses a spin coating step to form the polymer layer 48. Claims 77-79 are substantially similar to claims 72-73 in parent case 09/653,366.

Favorable consideration and allowance of claims 59-80 is respectfully requested. An Information Disclosure Statement is being filed concurrently with this Preliminary Amendment. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

Dated this 24th day of October 2003.